

4 Physical Layouts

This chapter contains the board layout and assembly drawings for the EVM.

4.1 Board Layout

Figure 2 shows the top assembly of the EVM. Figure 3 shows the top silk screen. Figure 4 shows the top layer. Figure 5 shows the bottom layer view.

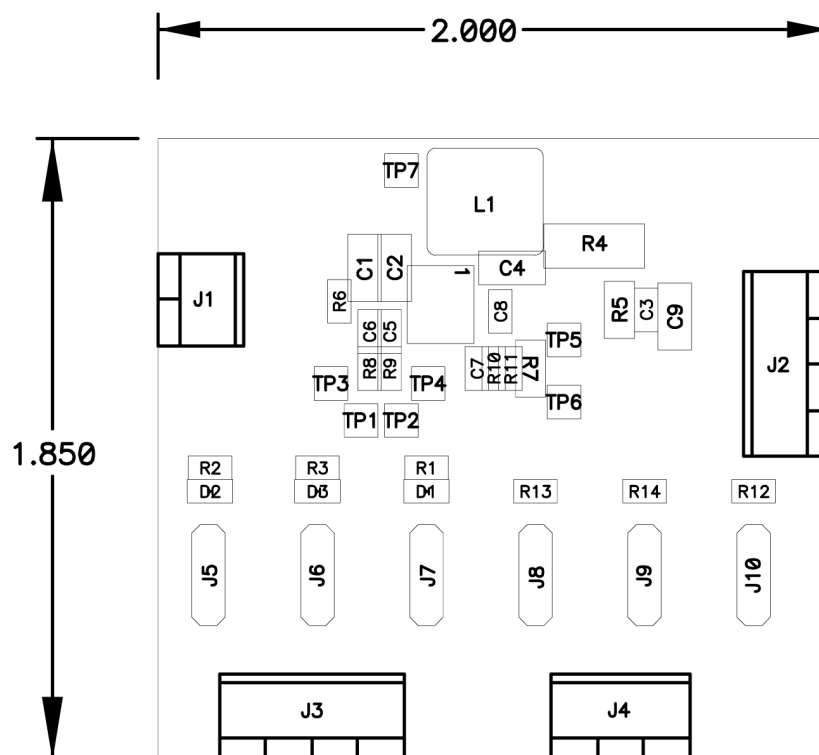


Figure 2. bq241xxEVM Top Assembly

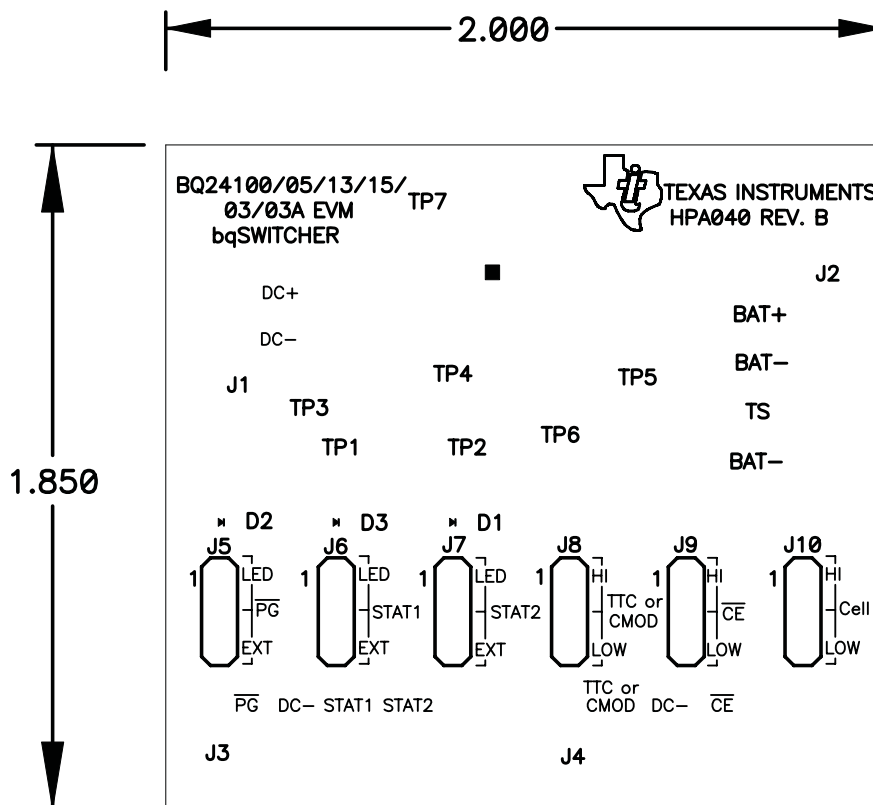


Figure 3. bq241xxEVM Top Silk Screen

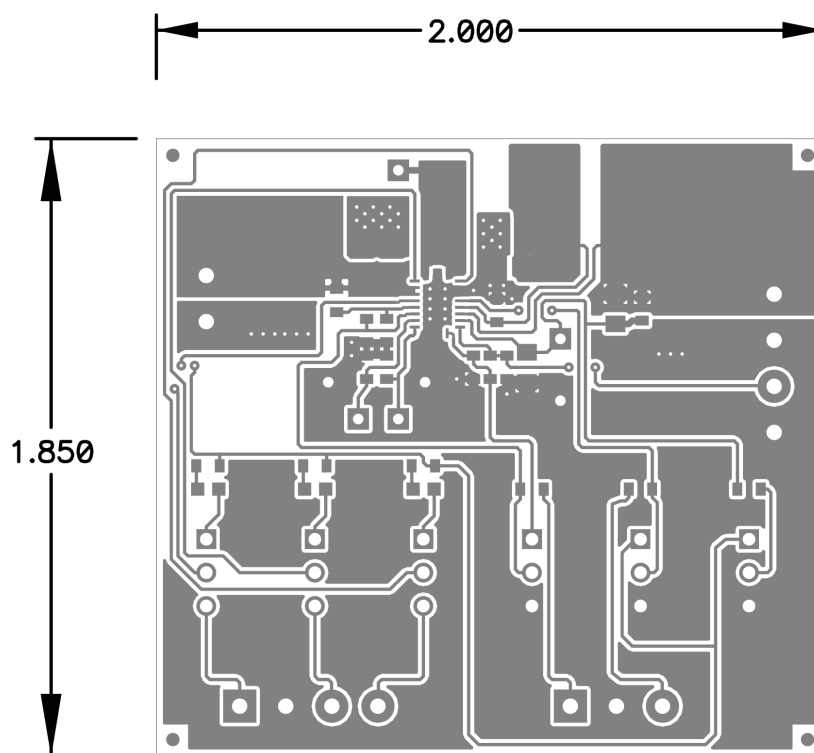


Figure 4. bq241xxEVM Top Layer

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